

E.O.T.①

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Response
#6
3-6-03
J. Curtis

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:)
Application No.: 09/864,055)
Filed: May 23, 2001)
For: Bonding Pad Structure and Method for)
Making Same)
Applicant: Ellis Lee et al.)
Examiner: Nguyen, Cuong Quang)
Art Unit 2811)

AMENDMENT AND RESPONSE TO 1st OFFICE ACTION

FAX RECEIVED

Assistant Commissioner of Patents and Trademarks
Washington, DC 20231

MAR 4 2003

TECHNOLOGY CENTER 2800

Sir:

The first office action mailed Nov. 06, 2002 (Paper No. 5) has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

REMARKS

This is a full and timely response to the outstanding Office Action mailed Nov. 06, 2002. Reconsideration and allowance of the application and presently pending claims, as amended, are respectfully requested.

Present Status of Patent Application

Claims 1-6 are presently pending in application. Claims 1-6 are rejected under 35 USC 102(e) as being anticipated by Jain et al. (US Patent No. 6,376,371, "Jain"). These rejections are respectfully traversed.

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